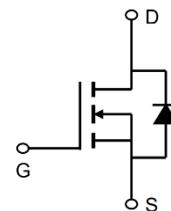


## Description

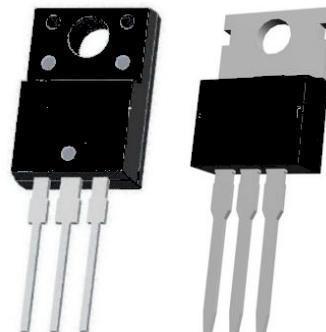
The AP7N65F/P is silicon N-channel Enhanced VDMOSFETs, is obtained by the self-aligned planar Technology which reduce the conduction loss, improve switching performance and enhance the avalanche energy. The transistor can be used in various power switching circuit for system miniaturization and higher efficiency.



## General Features

$V_{DS} = 650V$   $I_D = 7A$

$R_{DS(ON)} < 1.2\Omega$  @  $V_{GS}=10V$  (Type: 1.0 $\Omega$ )



## Application

Uninterruptible Power Supply(UPS)

Power Factor Correction (PFC)

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Value		Unit
		TO-220F	TO-220	
$VDSS$	Drain-Source Voltage ( $V_{GS} = 0V$ )	650		V
$ID$	Continuous Drain Current	7		A
$IDM$	Pulsed Drain Current (note1)	28		A
$VGS$	Gate-Source Voltage	$\pm 30$		V
$E_{AS}$	Single Pulse Avalanche Energy (note2)	247		mJ
$IAR$	Avalanche Current (note1)	7		A
$E_{AR}$	Repetitive Avalanche Energy note1)	18		mJ
$P_D$	Power Dissipation ( $T_c = 25^\circ C$ )	32.9		W
$T_J, T_{stg}$	Operating Junction and Storage Temperature Range	-55~+150		°C
$R_{thJC}$	Thermal Resistance, Junction-to-Case	3.8		°C/W
$R_{thJA}$	Thermal Resistance, Junction-to-Ambient	13.3		°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	650	685	--	V
IDSS	Zero Gate Voltage Drain Current	$V_{DS} = 650\text{V}, V_{GS} = 0\text{V}, T_J = 25^\circ\text{C}$	--	--	1	$\mu\text{A}$
IGSS	Gate-Source Leakage	$V_{GS} = \pm 30\text{V}$	--	--	$\pm 100$	nA
VGS(th)	Gate-Source Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	--	4.0	V
RDS(on)	Drain-Source On-Resistance (Note3)	$V_{GS} = 10\text{V}, I_D = 3.5\text{A}$	--	1.0	1.2	$\Omega$
$C_{iss}$	Input Capacitance	$V_{GS} = 0\text{V}, V_{DS} = 25\text{V}, f = 1.0\text{MHz}$	--	1000	--	pF
$C_{oss}$	Output Capacitance		--	101	--	
$C_{rss}$	Reverse Transfer Capacitance		--	1.5	--	
$Q_g$	Total Gate Charge	$V_{DD} = 520\text{V}, I_D = 7\text{A}, V_{GS} = 10\text{V}$	--	22	--	nC
$Q_{gs}$	Gate-Source Charge		--	4.3	--	
$Q_{gd}$	Gate-Drain Charge		--	13	--	
td(on)	Turn-on Delay Time	$V_{DD} = 325\text{V}, I_D = 7\text{A}, R_G = 25\Omega$	--	12	--	ns
$t_r$	Turn-on Rise Time		--	26	--	
td(off)	Turn-off Delay Time		--	29	--	
$t_f$	Turn-off Fall Time		--	27	--	
IS	Continuous Body Diode Current	$T_C = 25^\circ\text{C}$	--	--	7.0	A
ISM	Pulsed Diode Forward Current		--	--	28	A
$V_{SD}$	Body Diode Voltage	$T_J = 25^\circ\text{C}, I_{SD} = 7\text{A}, V_{GS} = 0\text{V}$	--	--	1.4	V
trr	Reverse Recovery Time	$V_{GS} = 0\text{V}, I_S = 7\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	--	389	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	2.04	--	$\mu\text{C}$

**Note :**

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The EAS data shows Max. rating . IAS = 4.5A, VDD = 50V, RG = 25  $\Omega$ , Starting TJ = 25  $^\circ\text{C}$
3. The test condition is Pulse Test: Pulse width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 1\%$
4. The power dissipation is limited by 150  $^\circ\text{C}$  junction temperature
5. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

## Typical Characteristics

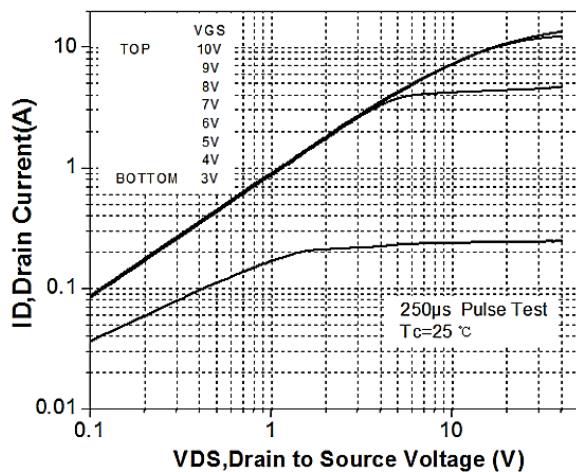


Figure 1. On-Region Characteristics

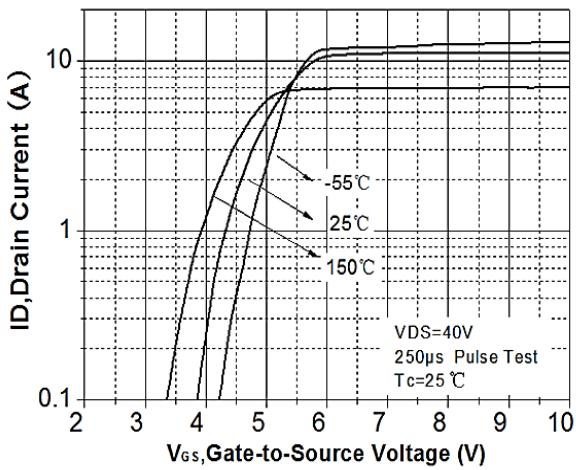


Figure 2. Transfer Characteristics

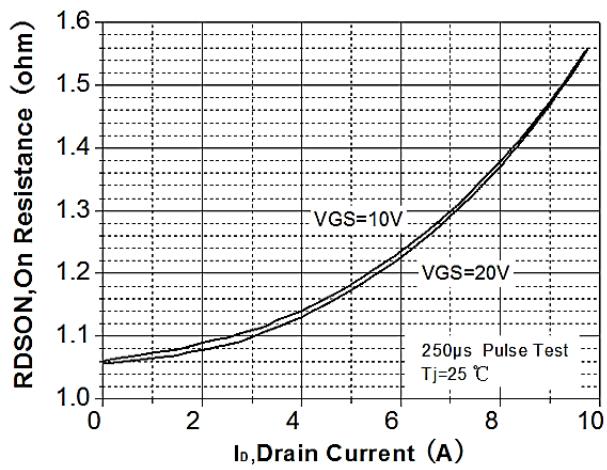


Figure 3. On-Resistance Variation vs Drain Current and Gate Voltage

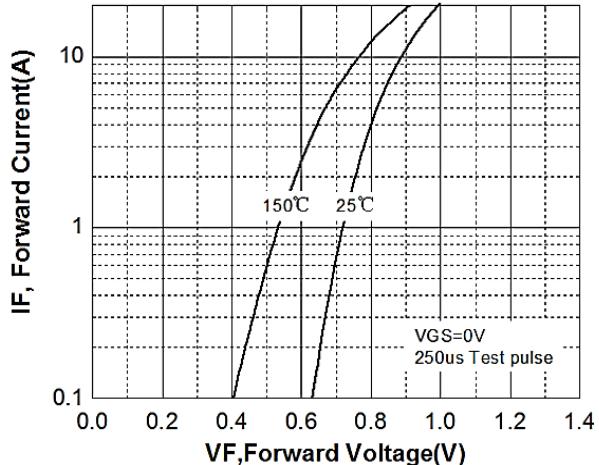


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

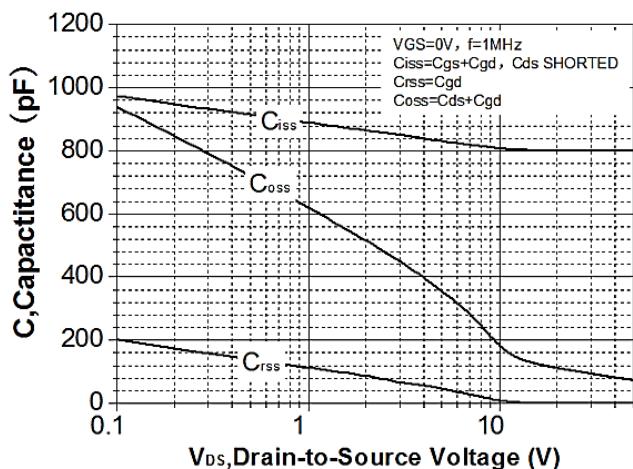


Figure 5. Capacitance Characteristics

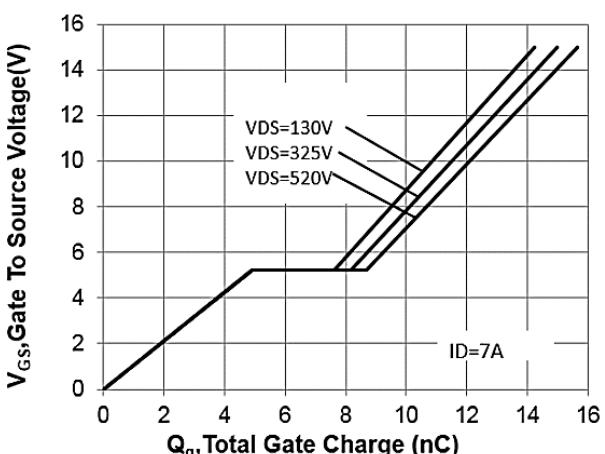
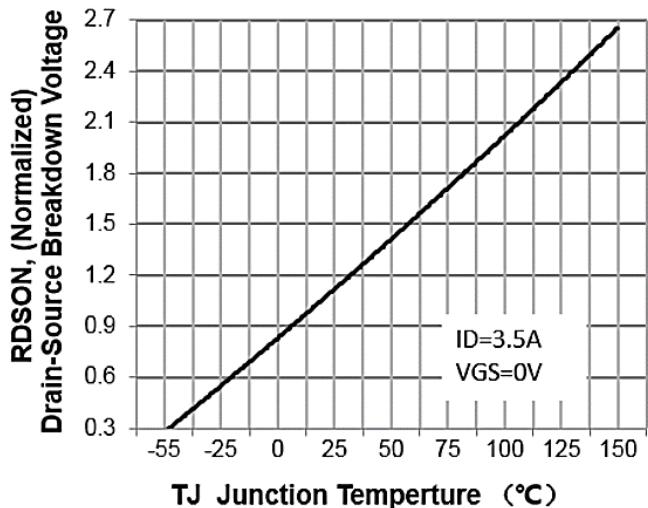
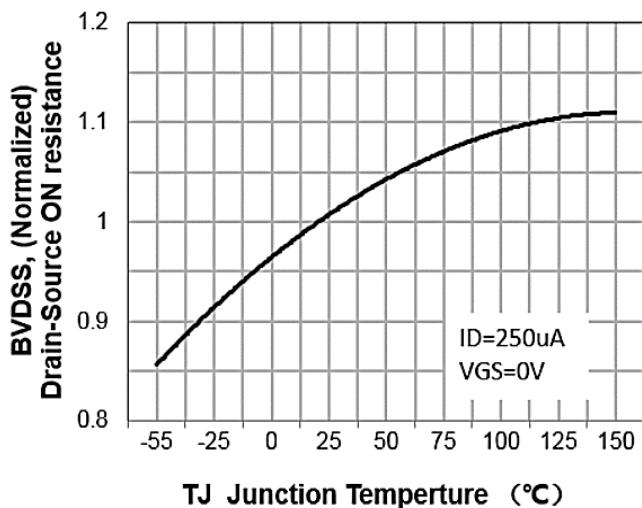
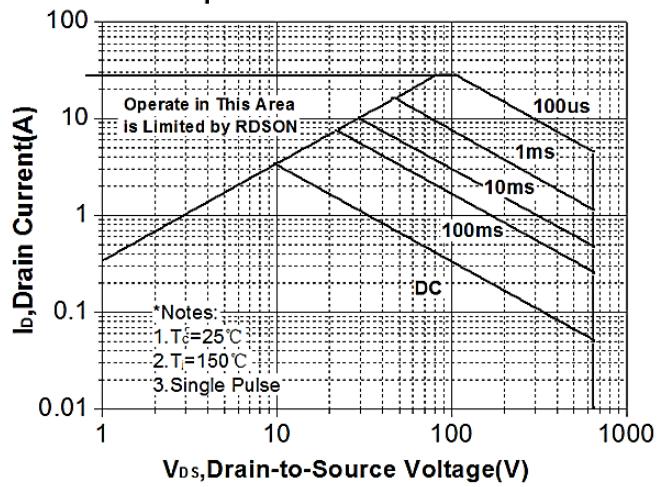


Figure 6. Gate Charge Characteristics

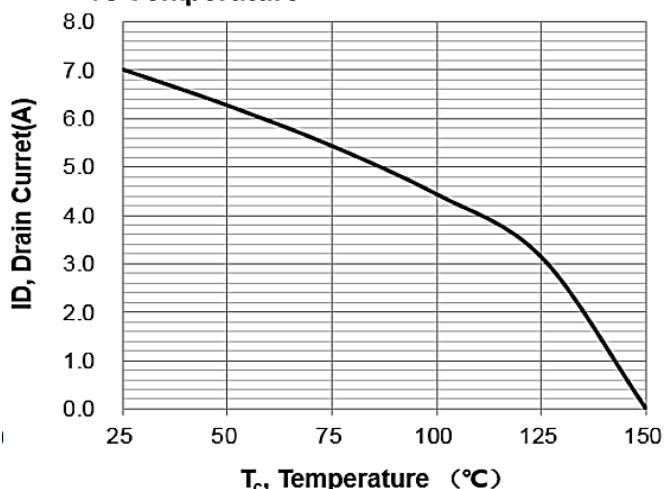


**Figure 7. Breakdown Voltage Variation vs Temperature**

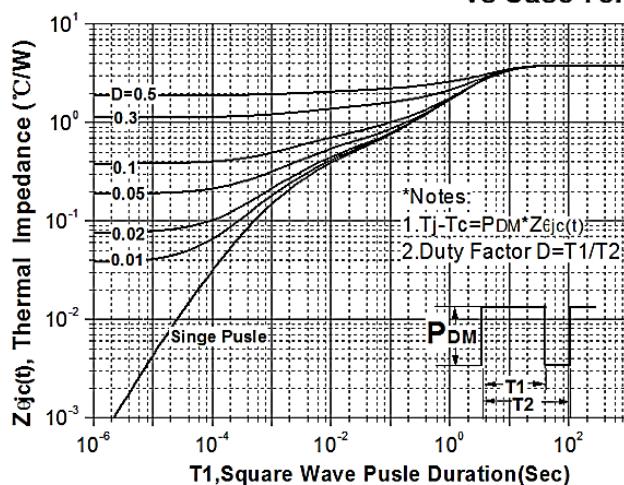
**Figure 8. On-Resistance Variation vs Temperature**



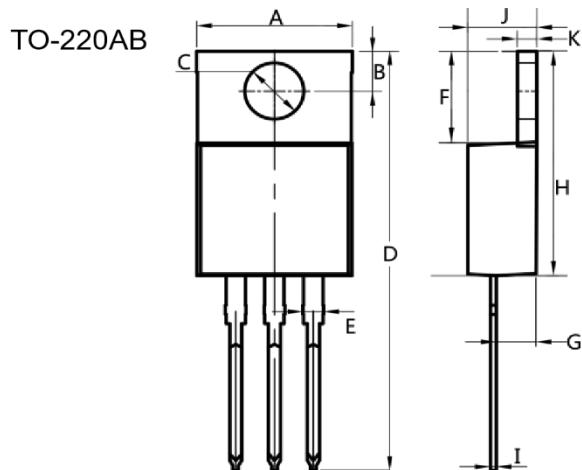
**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs Case Temperature**

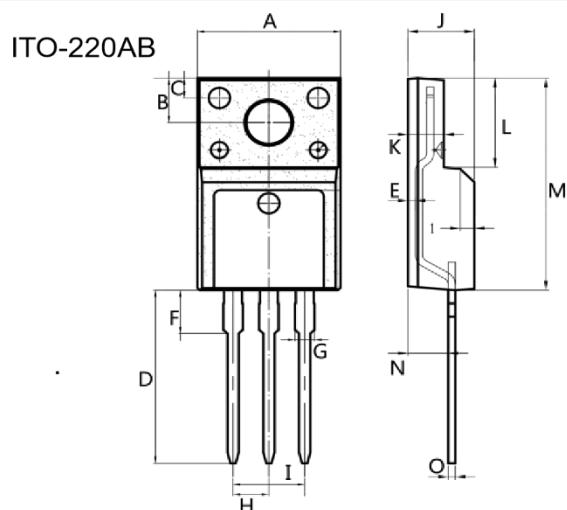


**Figure 11. Transient Thermal Response Curve**



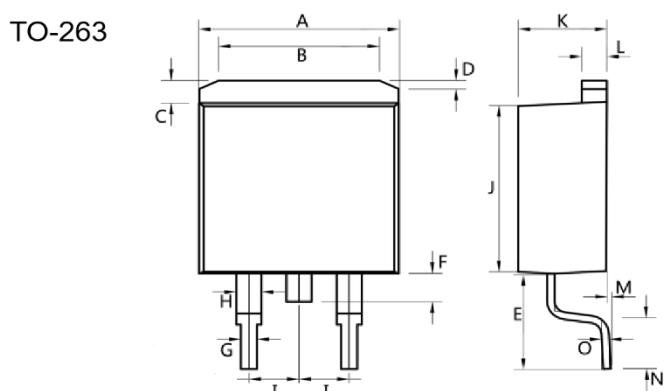
Dim.	Min.	Max.
A	10.0	10.4
B	2.5	3.0
C	3.5	4.0
D	28.0	30.0
E	1.1	1.5
F	6.2	6.6
G	2.9	3.3
H	15.0	16.0
I	0.35	0.45
J	4.3	4.7
K	1.2	1.4

All Dimensions in millimeter



Dim.	Min.	Max.
A	9.9	10.3
B	2.9	3.5
C	1.15	1.45
D	12.75	13.25
E	0.55	0.75
F	3.1	3.5
G	1.25	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.55	4.75
K	2.4	2.7
L	6.35	6.75
M	15.0	16.0
N	2.75	3.15
O	0.45	0.60

All Dimensions in millimeter



Dim.	Min.	Max.
A	10.0	10.5
B	7.25	7.75
C	1.3	1.5
D	0.55	0.75
E	5.0	6.0
F	1.4	1.6
G	0.75	0.95
H	1.15	1.35
I	Typ 2.54	
J	8.4	8.6
K	4.4	4.6
L	1.25	1.45
M	0.02	0.1
N	2.4	2.8
O	0.35	0.45

All Dimensions in millimeter